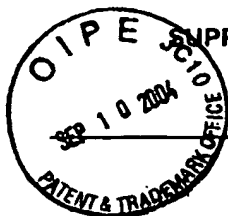


FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
ELM/001 Cont. 15APPLN. NO.
10/766,629APPLICANTS
Glenn J. LeedyCONF. NO.
3771FILING DATE
January 27, 2004GROUP ART UNIT
~~4765~~ 2818SUPPLEMENTAL INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
JH	4,500,905	02/19/1985	Shibata	357	68	
	4,939,568	07/03/1990	Kato, et al.	357	75	
	4,892,753	01/09/1990	Wang, et al.	427	579	
	5,000,113	03/19/1991	Wang, et al.	118	723	
	5,240,458	08/31/1993	Linglain, et al.	464	63	
	5,259,247	11/09/1993	Bantien	73	718	
	RE 34,893	04/04/1995	Fujii, et al.	257	419	
	RE 36,623	03/21/2000	Wang, et al.	427	579	
	6,087,284	07/11/2000	Brix, et al.	501	69	
JH	6,518,073	02/11/2003	Momohara	438	4	12/10/2001

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
JH	04-196,263	07/1992	Japan			(Abs)	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER INITIAL	
JH	Aboaf, J.A., "Stresses in SiO ₂ Films Obtained from the Thermal Decomposition of Tetraethylorthosilicate - Effect of Heat Treatment and Humidity," J. Electrochem. Soc.: Solid State Science; 116(12): 1732-1736 (Dec. 1969).
	Scheuerman, R.J., "Fabrication of Thin Dielectric Films with Low Internal Stresses," J. Vac. Sci. and Tech., 7(1): 143-146 (1970).
	Bailey, R., "Glass for Solid-State Devices: Glass film has low intrinsic compressive stress for isolating active layers of magnetic-bubble and other solid-state devices," NASA Tech Brief (1982).
	"Partitioning Function and Packaging of Integrated Circuits for Physical Security of Data," IBM Technical Disclosure Bulletin, IBM Corp.; 32(1): 46-49 (June 1989).
	Hsieh, et al., "Directional Deposition of Dielectric Silicon Oxide by Plasma Enhanced TEOS Process," 1989 Proceedings, Sixth International IEEE VLSI Multilevel Interconnection Conference, pp. 411-415 (1989).
JH	Tessier, et al., "An Overview of Dielectric Materials for Multichip Modules," SPE, Electrical & Electronic Div.; (6): 260-269 (1991).

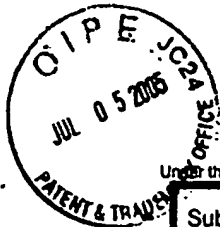
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Nov 2005

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PTO/SB/08A (10-01)

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Substitute for form 1449/PTO				Complete if known	
				Application Number	10/766,629 (Conf. No.: 3771)
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
(use as many sheets as necessary)				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
Sheet	1	of	1	Attorney Docket Number	ELM-1 CONT.15

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
TH		4,724,328	02/09/1988	Lischke	
		4,994,336	02/19/1991	Benecke et al.	
		5,358,909	10/25/1994	Hashiguchi et al.	
		5,514,628	05/07/1996	Enomoto et al.	
TH		5,620,915	04/15/1997	Chen et al.	

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ³
		Country Code ¹ - Number ² - Kind Code ³				
TH		GB 2,125,168	02/29/1984	Kouno		
TH		JP 02-037655	02/07/1990	Benecke et al.		

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ³
TH		"Christensens Physics of Diagnostic Radiology," Curry et al., pp.29-33, 1990...	

Examiner Signature	TH - TH HCO	Date Considered	Nov 2005
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All References Have Been Considered: _____
Examiner

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